

1. An apparatus for automatic airflow damping, the apparatus comprising:
an enclosure comprising an orifice configured to pass air;
an orifice cover having an open position configured to permit airflow through the orifice and a closed position configured to block airflow through the orifice; and
a cover actuator configured to move the orifice cover from the open position to the closed position in response to removal of an air moving device.
2. The apparatus of claim 1, wherein the cover actuator is a spring.
3. The apparatus of claim 2, wherein the spring is a torsion spring.
4. The apparatus of claim 1, further comprising a seal configured to block airflow around the orifice cover while in the closed position.
5. The apparatus of claim 1, wherein the seal comprises a layer of elastomeric material.
6. The apparatus of claim 1, wherein the orifice cover is a plate.
7. The apparatus of claim 1, further comprising a vent configured to pass air.
8. The apparatus of claim 1, wherein the enclosure is configured for positive air pressure.
9. The apparatus of claim 1, wherein the enclosure is configured for negative air pressure.

10. The apparatus of claim 1, wherein the cover is further configured with a mechanical hinge.

11. The apparatus of claim 1, further comprising an air-moving device configured to impel air through the orifice.

12. The apparatus of claim 11, wherein the air moving device is a fan.

13. The apparatus of claim 11, wherein the air moving device is a blower.

14. An apparatus for automatic airflow damping, the method comprising:

means for passing air through an orifice in an enclosure in order to cool electronic components in the enclosure; and

means for moving an orifice cover from an open position to a closed position in response to removal of an air moving device associated with the orifice.

15. The apparatus of claim 14, further comprising means for blocking airflow around the orifice cover while in the closed position.

16. A method for automatic airflow damping, the method comprising:

passing air through an orifice in an enclosure in order to cool electronic components in the enclosure; and

moving an orifice cover from an open position to a closed position in response to removal of an air moving device associated with the orifice.

17. The method of claim 16, wherein passing air through an orifice comprises blowing air into the enclosure.

18. The method of claim 14, wherein passing air through an orifice comprises exhausting air from the enclosure.

19. The method of claim 14, further comprising blocking airflow through the orifice.

20. A system utilizing automatic airflow damping, the system comprising:

a plurality of electronic components;

an enclosure configured to enclose the plurality of electronic components, the enclosure comprising an orifice configured to pass air;

an orifice cover having an open position configured to permit airflow through the orifice and a closed position configured to block airflow through the orifice; and

a cover actuator configured to move the orifice cover from the open position to the closed position in response to removal of an air moving device.